**Claims**

1. Mould half for a mould for transfer moulding encapsulating electronic components mounted on a carrier,
wherein a mould part to support the carrier has a contact surface that comprises a primary carrier support surface and a surrounding secondary surface, which surrounding secondary surface is supported by a drive for height adjustment of the secondary surface relative to the height of the primary carrier support surface.

2. Mould half according to claim 1, **characterised in that** the mould half comprises a mould half base that is stationary connected to the primary carrier support surface and that is adjustable connected with the surrounding secondary surface through the drive for height adjustment.

3. Mould half according to claim 1 or 2, **characterised in that** the drive for height adjustment of the secondary surface relative to the height of the primary carrier support surface is pressure or position controlled.

4. Mould half according to any of the preceding claims, **characterised in that** the drive for height adjustment of the secondary surface comprises at least one moveable wedge.

5. Mould half according to any of the preceding claims, **characterised in that** the drive for height adjustment of the secondary surface comprises at least one pneumatic or hydraulic cylinder.

6. Mould half according to any of the preceding claims, **characterised in that** the secondary surface also carries at least one guide for encapsulating material.

7. Mould half according to any of the preceding claims, **characterised in that** the primary and secondary surface are at least moveable between a position wherein the primary and secondary surface are on the same level and a position wherein the secondary surface is equal or more than the thickness of a carrier higher than the primary surface.

8. Mould half according to any of the preceding claims, **characterised in that** between the primary and secondary surface a gasket is located.

9. Mould half according to claim 8, **characterised in that** the gasket between primary and secondary surface is an operable gasket.

10. Mould half according to any of the preceding claims, **characterised in that** the mould half comprises a measurement sensor for measuring the relative position of the primary and secondary surfaces.

11. Mould for transfer moulding encapsulating electronic components mounted on a carrier, comprising at least two mould parts which are displaceable relative to each other, comprising a mould half according one of the preceding claims and an opposite clamping mould part.

12. Mould for transfer moulding encapsulating electronic components according to claim 11, **characterised in that** at least the opposite clamping mould part is provided with at least one mould cavity recessed in a contact side, with the contact side of the opposite clamping mould part with the at least one mould cavity being configured to engage on the carrier around the electronic components to be encapsulated.

13. Mould for transfer moulding encapsulating electronic components according to claim 11 or 12, **characterised in that** the contact side of the opposite clamping mould part is also provided with a feed channel for moulding material.

14. Mould for transfer moulding encapsulating electronic components according to any of the claims 11 - 13, **characterised in that** a moulding material feed (top edge) is provided between the opposite clamping mould parts and at least one of the clamping mould parts is provided with an aperture to hold the moulding material feed in a clamped position of the opposite clamping mould parts.

15. Method for transfer moulding encapsulating electronic components mounted on a carrier using a mould according to any of the claims 11 - 14, comprising the processing steps of:

a) positioning a carrier onto the primary surface of the carrier supporting mould half such that the electronic components face a mould cavity, wherein the secondary support surface is located on the same side of the electronic components carrying surface of the carrier as the primary support surface;
b) moving the mould parts towards each other, such that the mould parts are clamping the carrier between the primary support surface and the mould cavity recessed contact side, while the mould cavity is enclosing the electronic components to be encapsulated;
c) moving the secondary support surface towards the mould cavity recessed contact side of the opposite clamping mould part;
d) transferring a liquid moulding material via a feed channel in the mould cavity recessed contact side into the mould cavity;
e) at least partially curing the moulding material;
f) moving the mould parts apart from each other; and
g) removing the carrier with moulded electronic components from the primary support surface of the carrier supporting mould half.

16. Encapsulation method according to claim 15, **characterised in** that after moving the mould parts apart the secondary support surface is moved further away from the opposite mould part than the electronic components carrying surface of the carrier.

17. Encapsulation method according to claim 15 or 16, **characterised in that** during processing step c) the secondary support surface is moved towards the mould cavity recessed contact side of the opposite mould part until a specific closing pressure level of the secondary support surface is reached.

18. Method for transfer moulding encapsulating electronic components mounted on a carrier according to any of the claims 15 - 17, **characterised in that** the position of the secondary support surface relative to the primary support surface is registered and for instance fed back to an automatic process control.